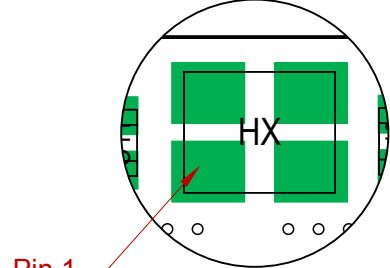


Notes:

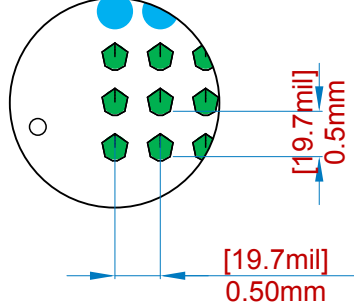
- 1 BT.TX/RX must be jumpered to pins marked in diagram. An accidental pin-swap occurred.
- 2 Vcore and de-coupling caps assume large >10uF caps on board.
- 3 Use Lead-Free solder paste on top-side to allow reflow of balls without reflow of top-side. 183 degC vs 217degC.
- 4 Next revision will not have HFX or LFX as internal ossillations are more than sufficient for normal operations. Maintain the 91 ohm calibration resistor for stability of DCO and Low frequency clock (32.768kHz)
- 5 Ensure 0.4mm BGA part uses NSMD pad definitions and 0.1mm lead in/out trace widths to maximise board yeild

DETAIL A (no markings for pin 1 on board , use diagram here) (Scale 8:1)

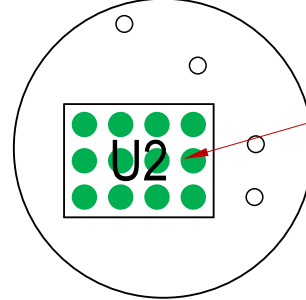


Pin 1

DETAIL A (Scale 12:1)

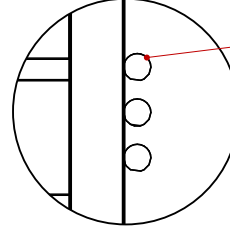


DETAIL BGA (Scale 12:1)



Note 5

DETAIL B (Scale 12:1)



11

A (no markings for pin 1 on board , use diagram here)

